



QSE-042-01-L-D-DP-A

QSE-014-01-F-D-DP-A

QSE-028-01-F-D-DP-A-RT1

0,80mm DIFFERENTIAL PAIR QSE-DP SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSE-DP

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au over 50µ" (1,27µm) Ni
- Current Rating:** Contacts: 2A @ 80°C
Ground Plane: 9.5A @ 80°C
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 225 VAC (5mm Stack Height)
- Max Cycles:** 100
- Unmating Force (-RT1 option):** -RT1 option increases unmating force up to 50%
- RoHS Compliant:** Yes
- Processing:**
 - Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x
 - Lead-Free Solderable:** Yes
 - SMT Lead Coplanarity:** (0,10mm) .004" max (014-042) (0,15mm) .006" max (056)
 - Board Stacking:** For applications requiring more than two connectors per board or 56 pairs or higher, contact ipg@samtec.com

Mates with: QTE-DP, EQDP (See Application Specific note)



Blade & Beam Design

Integral metal plane for power or ground



Application Notes

XAUI
PCI Express®
SATA

Download at www.samtec.com/appnote

STACK HEIGHT

QTE-DP LEAD STYLE	HEIGHT WITH QTE-DP
-01	(5,00) .198

Processing conditions will affect mated height.

ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

5mm Stack Height	Rated @ -3dB Insertion Loss
Differential Pair Signaling	8.5 GHz / 17 Gbps

Performance data for other stack heights available at www.samtec.com?QSE-DP



-014, -028, -042, -056
(14 pairs per bank)

-L
= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-C*
= Electro-Polished Selective
50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails

-K
= (8,25mm) .325" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel Packaging (-042 positions maximum)

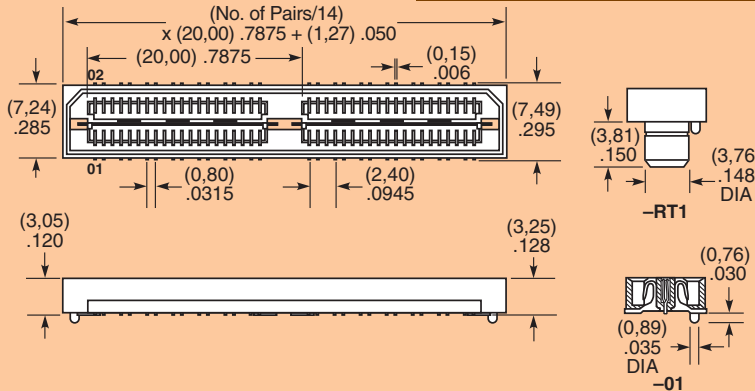
-RT1
= Retention Option (-042 positions maximum)

APPLICATION SPECIFIC OPTION

- 8mm, 11mm, 14mm, 15mm, 16mm, 19mm, 22mm, 25mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Guide Posts & Edge Mount
- 70 Pairs
- "Partitionable"-combine differential & single-ended banks in same connector
Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM